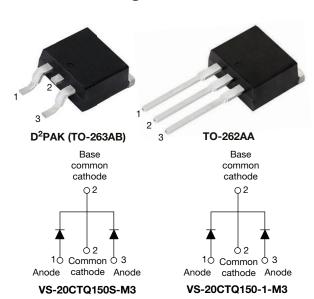
VS-20CTQ150S-M3, VS-20CTQ150-1-M3

Vishay Semiconductors

High Performance Schottky Rectifier, 2 x 10 A



PRIMARY CHARACTERISTICS						
I _{F(AV)} 2 x 10 A						
V _R	150 V					
V _F at I _F	0.66 V					
I _{RM} max.	5.0 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	1.0 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- 175 °C T_J operation
- Center tap configuration
- Low forward voltage drop
- High frequency operation



- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS									
SYMBOL CHARACTERISTICS VALUES UNITS									
I _{F(AV)}	Rectangular waveform	20	A						
V _{RRM}		150	V						
I _{FSM}	t _p = 5 μs sine	1030	А						
V _F	10 A _{pk} , T _J = 125 °C (per leg)	0.66	V						
T _J	Range	-55 to +175	°C						

VOLTAGE RATINGS						
PARAMETER	SYMBOL	VS-20CTQ150S-M3 VS-20CTQ150-1-M3	UNITS			
Maximum DC reverse voltage	V_{R}	150	V			
Maximum working peak reverse voltage	V_{RWM}	130	V			



VS-20CTQ150S-M3, VS-20CTQ150-1-M3

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ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDITIONS		VALUES	UNITS		
Maximum average forward	per leg							
current See fig. 5	per device	I _{F(AV)}	50 % duty cycle at T _C = 154 °C, rectangular waveform		20	•		
Maximum peak one cycle			5 μs sine or 3 μs rect. pulse	Following any rated	1030	Α		
non-repetitive surge current per leg See fig. 7		I _{FSM}	10 ms sine or 6 ms rect. pulse	load condition and with rated V _{RRM} applied	180			
Non-repetitive avalanche energy per leg		E _{AS}	$T_J = 25 ^{\circ}\text{C}$, $I_{AS} = 1 \text{A}$, $L = 2 \text{mH}$		1.0	mJ		
Repetitive avalanche current per leg		I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _R typical		1	Α		

ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS			UNITS			
		10 A	T _{.1} = 25 °C	0.80	0.88				
Maximum forward voltage drop per leg See fig. 1	V _{FM} ⁽¹⁾	20 A	1J=25 C	0.90	1.0	V			
		10 A	T 105 °C	0.63	0.66				
		20 A	- T _J = 125 °C	0.73	0.77				
Maximum reverse leakage current per leg	. (1)	T _J = 25 °C	V _R = Rated V _R	3.0	25	μΑ			
See fig. 2	I _{RM} ⁽¹⁾	T _J = 125 °C	v _R = nateu v _R	2.7	5.0	mA			
Typical junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal range 100 kHz to 1 MHz), 25 °C		-	280	pF			
Typical series inductance per leg	L _S	Measured lead to lead 5 mm from package body			8.0	nH			
Maximum voltage rate of change	dV/dt	Rated V _R		-	10 000	V/µs			

Note

 $^{^{(1)}\,}$ Pulse width $<300~\mu s,$ duty cycle <2~%

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	PARAMETER		TEST CONDITIONS	VALUES	UNITS		
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to +175	°C		
Maximum thermal resistance,	per leg	D	DC operation	2.0	°C/W		
junction to case	per package	R_{thJC}	DC operation	1.0			
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased (Only for TO-262)	0.50	G/11		
Approximate weight				2	g		
Approximate weight				0.07	oz.		
Maunting torque	minimum			6 (5)	kgf · cm		
Mounting torque	maximum			12 (10)	(lbf · in)		
Malian da inc			Case style D ² PAK (TO-263AB)	20CTC	150S		
Marking device			Case style TO-262AA	20CTQ	150-1		



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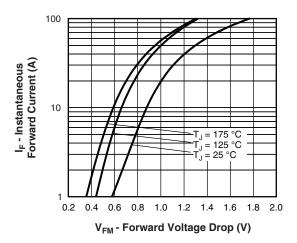


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

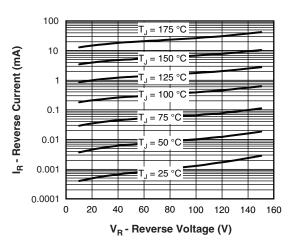


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

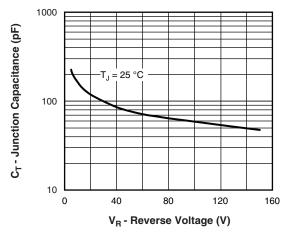


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

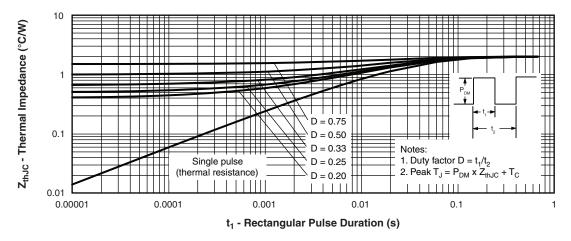


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

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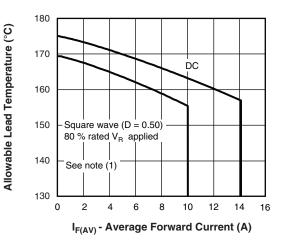


Fig. 5 - Maximum Average Forward Current vs.
Allowable Lead Temperature

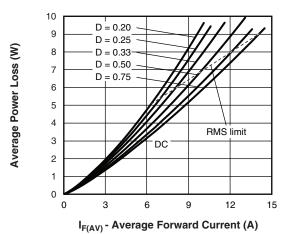


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

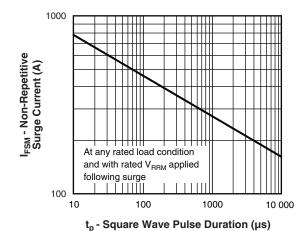


Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

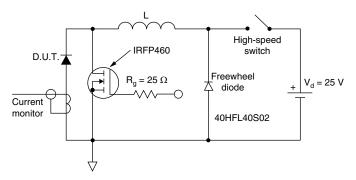


Fig. 8 - Unclamped Inductive Test Circuit

Note

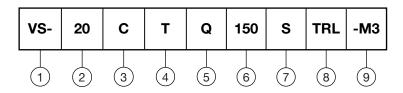
 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

VS-20CTQ150S-M3, VS-20CTQ150-1-M3

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (20 = 20 A)

C = common cathode

- T = TO-220

5 - Schottky "Q" series

Voltage rating (150 = 150 V)

7 - • $S = D^2PAK (TO-263AB)$

• -1 = TO-262AA

8 - • None = tube

• TRL = tape and reel (left oriented - for D²PAK (TO-263AB) only)

• TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)

9 - -M3 = halogen-free, RoHS -compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-20CTQ150S-M3	50	Antistatic plastic tubes					
VS-20CTQ150STRL-M3	800	13" diameter plastic tape and reel					
VS-20CTQ150STRR-M3	800	13" diameter plastic tape and reel					
VS-20CTQ150-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS					
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164			
Differsions	TO-262AA	www.vishay.com/doc?96165			
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444			
Part marking information	TO-262AA	www.vishay.com/doc?95443			
Packaging information		www.vishay.com/doc?96424			



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL		MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOIES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

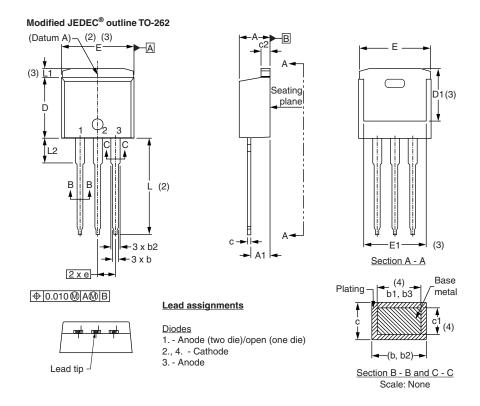
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.10	D BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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